

RELIABILITY MONITOR

DS1100Z-25 OCT '01 MONITOR

DEVICE	REVISION	DATE CD	LOT NUMBER	PINS	PACKAGE	WIDTH	ASSEMBLY SITE
DS1100	A3	0126	DK114601ADC	8	SOIC	150x1.4	ATP (Amkor, PI)
PROCESS		D6W-1P2M,HPVt,E2,TCZ PBL:GOI		Passivation w/Nov TEOS Oxide-Nitride			

Summary Data with Chi-Square Distribution Assumed.
 Stress Ambient Temperature and Voltage to
 Field Ambient Temperature And Voltage

Cf:	<u>60%</u>	Tuse:	<u>25 °C</u>
Ea:	<u>0.7</u>	Vuse:	<u>5.5 Volts</u>
β:	<u>0</u>		

JOB NO	DESCRIPT	CONDITION	QUANTITY	READPOINT	UNITS	NO OF FAILS
28535	HIGH VOLTAGE LIFE	125C, 6.0 VOLTS	77	336	HRS	0
		125C, 6.0 VOLTS	77	1000	HRS	0
		TOTAL:			FAIL RATE (Fits): 13	DEVICE HRS: 7.26E+07
28532	ULTRASOUND	J-STD-020	4	1	DYS	0
		TOTAL:				0
28533	STORAGE LIFE MOISTURE SOAK CONVECTION REFLOW	125C	238	24	HRS	
		85 C/85% R.H.	238	168	HRS	
		235C	238	3	PASS	0
		TOTAL:				0
28534	PRECONDITION U/S	J-STD-020	4	1	DYS	0
		TOTAL:				0
28536	TEMP CYCLE	-55C TO 125C	40	300	CYS	0
			40	1000	CYS	0
		TOTAL:				0
28537	BIASED MOISTURE	85/85, 5.5 VOLTS	77	500	HRS	
		TOTAL:				
28538	AUTOCLAVE	121C, 2 ATM STEAM, UNBIASED	40	168	HRS	0

PROJECT NO: 19605

RELIABILITY MONITOR

DS1100Z-25 OCT '01 MONITOR

DEVICE	REVISION	DATE CD	LOT NUMBER	PINS	PACKAGE	WIDTH	ASSEMBLY SITE
DS1100	A3	0126	DK114601ADC	8	SOIC	150x1.4	ATP (Amkor, PI)
PROCESS		D6W-1P2M,HPVt,E2,TCZ PBL:GOI		Passivation w/Nov TEOS Oxide-Nitride			

Summary Data with Chi-Square Distribution Assumed.
 Stress Ambient Temperature and Voltage to
 Field Ambient Temperature And Voltage

Cf:	<input type="text" value="60%"/>	Tuse:	<input type="text" value="25 °C"/>
Ea:	<input type="text" value="0.7"/>	Vuse:	<input type="text" value="5.5 Volts"/>
β:	<input type="text" value="0"/>		

JOB NO	DESCRIPT	CONDITION	QUANTITY	READPOINT	UNITS	NO OF FAILS
TOTAL:						0

RELIABILITY MONITOR

DS1100Z-25 JUL '02 MONITOR

DEVICE	REVISION	DATE CD	LOT NUMBER	PINS	PACKAGE	WIDTH	ASSEMBLY SITE
DS1100	A3	0230	DE120202AFB	8	SOIC	150x1.4	OSEP
PROCESS D6W-1P2M,HPVt,E2,TCZ PBL:GOI Passivation w/Nov TEOS Oxide-Nitride							

Summary Data with Chi-Square Distribution Assumed.
 Stress Ambient Temperature and Voltage to
 Field Ambient Temperature And Voltage

Cf:	60%	Tuse:	25 °C
Ea:	0.7	Vuse:	5.5 Volts
β:	0		

JOB NO	DESCRIPT	CONDITION	QUANTITY	READPOINT	UNITS	NO OF FAILS
30192	HIGH VOLTAGE LIFE	125C, 6.0 VOLTS	80	500	HRS	
TOTAL:			FAIL RATE (Fits):		DEVICE HRS: 3.77E+07	
30189	ULTRASOUND	J-STD-020	4	1	DYS	0
TOTAL:			0			
30190	STORAGE LIFE	125C	241	24	HRS	
	MOISTURE SOAK	85 C/85% R.H.	241	168	HRS	
	CONVECTION REFLOW	235C	241	3	PASS	0
TOTAL:			0			
30191	PRECONDITION U/S	J-STD-020	4	1	DYS	0
TOTAL:			0			
30193	TEMP CYCLE	-55C TO 125C	40	500	CYS	
TOTAL:						
30194	BIASED MOISTURE	85/85, 5.5 VOLTS	77	500	HRS	
TOTAL:						
30195	AUTOCLAVE	121C, 2 ATM STEAM, UNBIASED	40	168	HRS	
TOTAL:						

PROJECT NO: 24619

RELIABILITY MONITOR

DS1267-010 AUG '02 MONITOR

DEVICE	REVISION	DATE CD	LOT NUMBER	PINS	PACKAGE	WIDTH	ASSEMBLY SITE
DS1267	A1	0237	DM234023AFB	20	TSSOP	4.4x0.9	Carsem
PROCESS	1P, 1M, 1.2um, II Poly1, TEOS Passivation w/Nov TEOS Oxide-Nitride						

Summary Data with Chi-Square Distribution Assumed.
 Stress Ambient Temperature and Voltage to
 Field Ambient Temperature And Voltage

Cf:	60%	Tuse:	25 °C
Ea:	0.7	Vuse:	5.5 Volts
β:	0		

JOB NO	DESCRIPT	CONDITION	QUANTITY	READPOINT	UNITS	NO OF FAILS
30199	HIGH VOLTAGE LIFE	125C, 6.0 V, -4.0V	79	500	HRS	
TOTAL:			FAIL RATE (Fits):		DEVICE HRS: 3.73E+07	
30197	STORAGE LIFE	125C	241	24	HRS	
	MOISTURE SOAK	85 C/85% R.H.	241	168	HRS	
	CONVECTION REFLOW	235C	241	3	PASS	0
TOTAL:			0			
30200	TEMP CYCLE	-55C TO 125C	40	500	CYS	
TOTAL:						
30201	BIASED MOISTURE	85/85, 5.5 VOLTS	77	500	HRS	
TOTAL:						
30202	AUTOCLAVE	121C, 2 ATM STEAM, UNBIASED	40	96	HRS	
TOTAL:						

PROJECT NO: 24618

RELIABILITY MONITOR

DS1302 SEP '02 MONITOR

DEVICE	REVISION	DATE CD	LOT NUMBER	PINS	PACKAGE	WIDTH	ASSEMBLY SITE
DS1302	A4	0226	DE244426AA	8	PDIP	300	CPS (ChipPac, China
PROCESS 1P, 2M, 0.8um, ESD Pdepletion,HP Vts, Passivation w/Nov TEOS Oxide-Nitride							

Summary Data with Chi-Square Distribution Assumed.
 Stress Ambient Temperature and Voltage to
 Field Ambient Temperature And Voltage

Cf:	<u>60%</u>	Tuse:	<u>25 °C</u>
Ea:	<u>0.7</u>	Vuse:	<u>5.5 Volts</u>
β:	<u>0</u>		

JOB NO	DESCRIPT	CONDITION	QUANTITY	READPOINT	UNITS	NO OF FAILS
30178	HIGH VOLTAGE LIFE	125C, 6.0 VOLTS	80	500	HRS	0
		125C, 6.0 VOLTS	80	1000	HRS	0
		TOTAL:			FAIL RATE (Fits): 12	DEVICE HRS: 7.55E+07
30179	TEMP CYCLE	-55C TO 125C	45	500	CYS	0
			45	1000	CYS	0
		TOTAL:				
30180	BIASED MOISTURE	85/85, 5.5 VOLTS	77	500	HRS	0
			77	1000	HRS	0
		TOTAL:				
30181	AUTOCLAVE	121C, 2 ATM STEAM, UNBIASED	45	168	HRS	0
		TOTAL:				0

PROJECT NO: 24638

RELIABILITY MONITOR

DS1620 JUL '02 MONITOR

DEVICE	REVISION	DATE CD	LOT NUMBER	PINS	PACKAGE	WIDTH	ASSEMBLY SITE
DS1620	D1	0114	DH052446AAF	8	SOIC	208x1.9	CPS (ChipPac, China
PROCESS	D8W-1P1M,HPVt,E2		LOCOS:GOI	Passivation w/Nov TEOS Oxide-Nitride			

Summary Data with Chi-Square Distribution Assumed.
 Stress Ambient Temperature and Voltage to
 Field Ambient Temperature And Voltage

Cf:	60%	Tuse:	25 °C
Ea:	0.7	Vuse:	5.5 Volts
β:	0		

JOB NO	DESCRIPT	CONDITION	QUANTITY	READPOINT	UNITS	NO OF FAILS
30102	HIGH VOLTAGE LIFE	125C, 7.0 VOLTS	79	500	HRS	0
		125C, 7.0 VOLTS	79	1000	HRS	0
		TOTAL:			FAIL RATE (Fits): 12	DEVICE HRS: 7.45E+07
30099	ULTRASOUND	J-STD-020	4	7	DYS	0
		TOTAL:				0
30100	STORAGE LIFE MOISTURE SOAK CONVECTION REFLOW	125C	244	24	HRS	
		85 C/85% R.H.	244	168	HRS	
		235C	244	3	PASS	0
		TOTAL:				0
30101	PRECONDITION U/S	J-STD-020	4	7	DYS	0
		TOTAL:				0
30103	TEMP CYCLE	-55C TO 125C	40	500	CYS	2
			38	1000	CYS	0
		TOTAL:				2

FAILURE MODE	VERIFICATION	FA NUMBER	FAILURE MECHANISM
ICC STANDBY	(#1)		
ICC ACTIVE	(#2)		

30104	BIASED MOISTURE	85/85, 5.5 VOLTS	70	500	HRS	0
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PROJECT NO: 24459

RELIABILITY MONITOR

DS1620 JUL '02 MONITOR

DEVICE	REVISION	DATE CD	LOT NUMBER	PINS	PACKAGE	WIDTH	ASSEMBLY SITE
DS1620	D1	0114	DH052446AAF	8	SOIC	208x1.9	CPS (ChipPac, China
PROCESS		D8W-1P1M,HPVt,E2		LOCOS:GOI		Passivation w/Nov TEOS Oxide-Nitride	

Summary Data with Chi-Square Distribution Assumed.
 Stress Ambient Temperature and Voltage to
 Field Ambient Temperature And Voltage

Cf:	<u>60%</u>	Tuse:	<u>25 °C</u>
Ea:	<u>0.7</u>	Vuse:	<u>5.5 Volts</u>
β:	<u>0</u>		

JOB NO	DESCRIPT	CONDITION	QUANTITY	READPOINT	UNITS	NO OF FAILS
			70	1000	HRS	0
		TOTAL:				0
30105	WRITE CYCLE STRESS	85 C, 7.0 VOLTS	50	50	KCYS	0
		TOTAL:				0
30106	STORAGE LIFE	150C	50	500	HRS	0
			50	1000	HRS	0
		TOTAL:				0

PROJECT NO: 24459

RELIABILITY MONITOR

DS1621 SEP '02 MONITOR

DEVICE	REVISION	DATE CD	LOT NUMBER	PINS	PACKAGE	WIDTH	ASSEMBLY SITE
DS1621	A7	0232	DK103506AAB	8	SOIC	150x1.4	ATP (Amkor, PI)
PROCESS		D8W-1P1M,HPVt,E2		LOCOS:GOI		Passivation w/Nov TEOS Oxide-Nitride	

Summary Data with Chi-Square Distribution Assumed.
 Stress Ambient Temperature and Voltage to
 Field Ambient Temperature And Voltage

Cf:	60%	Tuse:	25 °C
Ea:	0.7	Vuse:	5.5 Volts
β:	0		

JOB NO	DESCRIPT	CONDITION	QUANTITY	READPOINT	UNITS	NO OF FAILS
30117	HIGH VOLTAGE LIFE	125C, 7.0 VOLTS	77	500	HRS	0
		125C, 7.0 VOLTS	77	1000	HRS	0
		TOTAL:			FAIL RATE (Fits):	13
30114	ULTRASOUND	J-STD-020	4	7	DYS	0
		TOTAL:				
30115	STORAGE LIFE MOISTURE SOAK CONVECTION REFLOW	125C	241	24	HRS	
		85 C/85% R.H.	241	168	HRS	
		235C	241	3	PASS	0
		TOTAL:				
30116	PRECONDITION U/S	J-STD-020	4	7	DYS	0
		TOTAL:				
30118	TEMP CYCLE	-55C TO 125C	40	500	CYS	0
			40	1000	CYS	0
		TOTAL:				
30119	BIASED MOISTURE	85/85, 5.5 VOLTS	70	500	HRS	0
			70	1000	HRS	0
		TOTAL:				

PROJECT NO: 24460

RELIABILITY MONITOR

DS1621 SEP '02 MONITOR

DEVICE	REVISION	DATE CD	LOT NUMBER	PINS	PACKAGE	WIDTH	ASSEMBLY SITE
DS1621	A7	0232	DK103506AAB	8	SOIC	150x1.4	ATP (Amkor, PI)
PROCESS		D8W-1P1M,HPVt,E2 LOCOS:GOI		Passivation w/Nov TEOS Oxide-Nitride			

Summary Data with Chi-Square Distribution Assumed.
 Stress Ambient Temperature and Voltage to
 Field Ambient Temperature And Voltage

Cf: <input style="width: 50px;" type="text" value="60%"/>	Tuse: <input style="width: 50px;" type="text" value="25 °C"/>
Ea: <input style="width: 50px;" type="text" value="0.7"/>	Vuse: <input style="width: 50px;" type="text" value="5.5 Volts"/>
β: <input style="width: 50px;" type="text" value="0"/>	

JOB NO	DESCRIPT	CONDITION	QUANTITY	READPOINT	UNITS	NO OF FAILS
30120	WRITE CYCLE STRESS	85 C, 7.0 VOLTS	50	50	KCYS	0
		TOTAL:				0
30121	STORAGE LIFE	150C	50	500	HRS	0
			50	1000	HRS	
		TOTAL:				0

PROJECT NO: 24460

RELIABILITY MONITOR

DS1803-010 NOV '01 MONITOR

DEVICE	REVISION	DATE CD	LOT NUMBER	PINS	PACKAGE	WIDTH	ASSEMBLY SITE
DS1803	A2	0143	DK122629AAB	16	SOIC	150x1.4	ATP (Amkor, PI)
PROCESS 1P, 2M, 0.8um, PdplDiode, WJ Passivation w/Nov TEOS Oxide-Nitride							

Summary Data with Chi-Square Distribution Assumed.
 Stress Ambient Temperature and Voltage to
 Field Ambient Temperature And Voltage

Cf:	<u>60%</u>	Tuse:	<u>25 °C</u>
Ea:	<u>0.7</u>	Vuse:	<u>5.5 Volts</u>
β:	<u>0</u>		

JOB NO	DESCRIPT	CONDITION	QUANTITY	READPOINT	UNITS	NO OF FAILS
28558	HIGH VOLTAGE LIFE	125C, 7.0 VOLTS	80	336	HRS	0
		125C, 7.0 VOLTS	80	336	HRS	0
		125C, 7.0 VOLTS	80	336	HRS	0
		TOTAL:	FAIL RATE (Fits):	12	DEVICE HRS: 7.61E+07	
28555	ULTRASOUND	J-STD-020	4	1	DYS	0
		TOTAL:				0
28556	STORAGE LIFE MOISTURE SOAK CONVECTION REFLOW	125C	241	24	HRS	
		85 C/85% R.H.	241	168	HRS	
		235C	241	3	PASS	0
		TOTAL:				0
28557	PRECONDITION U/S	J-STD-020	4	2	DYS	0
		TOTAL:				0
28559	TEMP CYCLE	-55C TO 125C	40	300	CYS	0
			40	1000	CYS	0
		TOTAL:				0
28560	BIASED MOISTURE	85/85, 5.5 VOLTS	77	274	HRS	0
			77	959	HRS	0

PROJECT NO: 20883

RELIABILITY MONITOR

DS1803-010 NOV '01 MONITOR

DEVICE	REVISION	DATE CD	LOT NUMBER	PINS	PACKAGE	WIDTH	ASSEMBLY SITE
DS1803	A2	0143	DK122629AAB	16	SOIC	150x1.4	ATP (Amkor, PI)
PROCESS 1P, 2M, 0.8um, PdplDiode, WJ Passivation w/Nov TEOS Oxide-Nitride							

Summary Data with Chi-Square Distribution Assumed.
 Stress Ambient Temperature and Voltage to
 Field Ambient Temperature And Voltage

Cf:	<u>60%</u>	Tuse:	<u>25</u> °C
Ea:	<u>0.7</u>	Vuse:	<u>5.5</u> Volts
β:	<u>0</u>		

JOB NO	DESCRIPT	CONDITION	QUANTITY	READPOINT	UNITS	NO OF FAILS
		TOTAL:				0
28561	AUTOCLAVE	121C, 2 ATM STEAM, UNBIASED	37	168	HRS	0
		TOTAL:				0

RELIABILITY MONITOR

DS1803-010 APR '02 MONITOR

DEVICE	REVISION	DATE CD	LOT NUMBER	PINS	PACKAGE	WIDTH	ASSEMBLY SITE
DS1803	A2	0204	DE113317AAB	16	SOIC	150x1.4	OSEP
PROCESS 1P, 2M, 0.8um, PdplDiode, Ti/TiN M1+M2 Passivation w/Nov TEOS Oxide-Nitride							

Summary Data with Chi-Square Distribution Assumed.
 Stress Ambient Temperature and Voltage to
 Field Ambient Temperature And Voltage

Cf:	60%	Tuse:	25 °C
Ea:	0.7	Vuse:	5.5 Volts
β:	0		

JOB NO	DESCRIPT	CONDITION	QUANTITY	READPOINT	UNITS	NO OF FAILS
29506	HIGH VOLTAGE LIFE	125C, 7.0 VOLTS	80	500	HRS	0
		125C, 7.0 VOLTS	80	500	HRS	0
		125C, 7.0 VOLTS	80	500	HRS	0
		125C, 7.0 VOLTS	80	1000	HRS	0
		125C, 7.0 VOLTS	80	1000	HRS	0
		125C, 7.0 VOLTS	80	1000	HRS	0
		TOTAL:		FAIL RATE (Fits):	4	DEVICE HRS: 2.26E+08
29503	ULTRASOUND	J-STD-020	4	2	DYS	0
		TOTAL:			0	
29504	STORAGE LIFE MOISTURE SOAK CONVECTION REFLOW	125C	241	24	HRS	
		85 C/85% R.H.	241	168	HRS	
		235C	241	3	PASS	0
		TOTAL:			0	
29505	PRECONDITION U/S	J-STD-020	4	2	DYS	0
		TOTAL:			0	
29507	TEMP CYCLE	-55C TO 125C	40	500	CYS	0
			40	1000	CYS	0

PROJECT NO: 21799

RELIABILITY MONITOR

DS1803-010 APR '02 MONITOR

DEVICE	REVISION	DATE CD	LOT NUMBER	PINS	PACKAGE	WIDTH	ASSEMBLY SITE
DS1803	A2	0204	DE113317AAB	16	SOIC	150x1.4	OSEP
PROCESS 1P, 2M, 0.8um, PdplDiode, Ti/TiN M1+M2 Passivation w/Nov TEOS Oxide-Nitride							

Summary Data with Chi-Square Distribution Assumed.
 Stress Ambient Temperature and Voltage to
 Field Ambient Temperature And Voltage

Cf:	60%	Tuse:	25 °C
Ea:	0.7	Vuse:	5.5 Volts
β:	0		

JOB NO	DESCRIPT	CONDITION	QUANTITY	READPOINT	UNITS	NO OF FAILS
TOTAL:						0
29508	BIASED MOISTURE	85/85, 5.5 VOLTS	77	500	HRS	0
			76	1000	HRS	0
TOTAL:						0
29509	AUTOCLAVE	121C, 2 ATM STEAM, UNBIASED	39	168	HRS	0
TOTAL:						0

PROJECT NO: 21799

RELIABILITY MONITOR

DS1803-010 OCT '02 MONITOR

DEVICE	REVISION	DATE CD	LOT NUMBER	PINS	PACKAGE	WIDTH	ASSEMBLY SITE
DS1803	A2	0234	DK236047AAB	16	SOIC	150x1.4	ATP (Amkor, PI)

JOB_NO	DESCRIPTION	CONDITION	QUANTITY	READPOINT	UNITS	NO OF FAILS
30226	ULTRASOUND	J-STD-020	4	2	DYS	0
		TOTAL:				0
30227	STORAGE LIFE	125C	241	24	HRS	
	MOISTURE SOAK	85 C/85% R.H.	241	168	HRS	
	CONVECTION REFLOW	235C	241	3	PASS	
		TOTAL:				

PROJECT NO: 24620

RELIABILITY MONITOR

DS21352 AUG '02 MONITOR, D.P.

DEVICE	REVISION	DATE CD	LOT NUMBER	PINS	PACKAGE	WIDTH	ASSEMBLY SITE
DS21352	A4	0240	DC039494AAA	100	LQFP	14x14x	Stats
PROCESS 2P, 2M, 0.6um, P2Cap, PdD, HP Vts, GO Laser/TEOS Ox - Pass/Nit - Gen.LaserPrb							

Summary Data with Chi-Square Distribution Assumed.
 Stress Ambient Temperature and Voltage to
 Field Ambient Temperature And Voltage

Cf:	60%	Tuse:	25 °C
Ea:	0.7	Vuse:	5.5 Volts
β:	0		

JOB NO	DESCRIPT	CONDITION	QUANTITY	READPOINT	UNITS	NO OF FAILS
30219	HIGH VOLTAGE LIFE	125C, 6.0 VOLTS	77	500	HRS	0
		125C, 6.0 VOLTS	77	1000	HRS	0
TOTAL:			13	DEVICE HRS: 7.26E+07		0
FAILURE MODE		VERIFICATION	FA NUMBER	FAILURE MECHANISM		
IBO2_3V		(#1,2)				
30217	STORAGE LIFE	125C	241	24	HRS	
	MOISTURE SOAK	30C/60% R.H.	241	192	HRS	
	CONVECTION REFLOW	235C	241	3	PASS	0
TOTAL:						0
30220	TEMP CYCLE	-55C TO 125C	77	500	CYS	0
			77	1000	CYS	0
TOTAL:						0
30221	HAST, NO BIAS	130C, 85% R.H.	72	96	HRS	0
TOTAL:						0

PROJECT NO: 24622

RELIABILITY MONITOR

DS2154 NOV '02 MONITOR, D.P.

DEVICE	REVISION	DATE CD	LOT NUMBER	PINS	PACKAGE	WIDTH	ASSEMBLY SITE
DS2154	A2	0230	DC102671AAA	100	LQFP	14x14x	Stats
PROCESS D8R-2P2M,HPVt,NDR0M,N+ESD,Laser Laser/TEOS Ox - Pass/Nit - Gen.LaserPrb							

Summary Data with Chi-Square Distribution Assumed.
 Stress Ambient Temperature and Voltage to
 Field Ambient Temperature And Voltage

Cf:	60%	Tuse:	25 °C
Ea:	0.7	Vuse:	5.5 Volts
β:	0		

JOB NO	DESCRIPT	CONDITION	QUANTITY	READPOINT	UNITS	NO OF FAILS
30236	HIGH VOLTAGE LIFE	125C, 6.0 VOLTS	80	500	HRS	2
TOTAL:			83	FAIL RATE (Fits): DEVICE HRS: 3.73E+07		2
FAILURE MODE		VERIFICATION	FA NUMBER		FAILURE MECHANISM	
RCHANB		# 1,2				
30234	STORAGE LIFE	125C	241	24	HRS	
	MOISTURE SOAK	30C/60% R.H.	241	192	HRS	
	CONVECTION REFLOW	235C	241	3	PASS	0
TOTAL:						0
30237	TEMP CYCLE	-55C TO 125C	78	500	CYS	0
TOTAL:						0
30238	HAST, NO BIAS	130C, 85% R.H.	77	200	HRS	0
TOTAL:						0

PROJECT NO: 24658

RELIABILITY MONITOR

DS21S07 FEB '02 MONITOR

DEVICE	REVISION	DATE CD	LOT NUMBER	PINS	PACKAGE	WIDTH	ASSEMBLY SITE
DS21S07	C1-A	0112	DM048483ACB	20	TSSOP	4.4x0.9	Carsem
PROCESS 1P, 1M, 0.8um,Neg ZTC P1R,PdpID,Low Laser/Nit - Pass/Nit - General LaserPrb							

Summary Data with Chi-Square Distribution Assumed.
 Stress Ambient Temperature and Voltage to
 Field Ambient Temperature And Voltage

Cf:	<u>60%</u>	Tuse:	<u>25 °C</u>
Ea:	<u>0.7</u>	Vuse:	<u>5.5 Volts</u>
β:	<u>0</u>		

JOB NO	DESCRIPT	CONDITION	QUANTITY	READPOINT	UNITS	NO OF FAILS
28808	HIGH VOLTAGE LIFE	125C, 7.0 VOLTS	77	336	HRS	0
		125C, 7.0 VOLTS	77	1000	HRS	0
		TOTAL:			FAIL RATE (Fits): 13	DEVICE HRS: 7.26E+07
28805	ULTRASOUND	J-STD-020	4	5	DYS	0
		TOTAL:				0
28806	STORAGE LIFE MOISTURE SOAK CONVECTION REFLOW	125C	243	48	HRS	
		85 C/85% R.H.	243	168	HRS	
		235C	243	3	PASS	0
		TOTAL:				0
28807	PRECONDITION U/S	J-STD-020	4	7	DYS	0
		TOTAL:				0
28809	TEMP CYCLE	-55C TO 125C	45	300	CYS	0
			45	1000	CYS	0
		TOTAL:				0
28810	BIASED MOISTURE	85/85, 5.5 VOLTS	77	274	HRS	0
			77	959	HRS	0
		TOTAL:				0

PROJECT NO: 21346

RELIABILITY MONITOR

DS21S07 FEB '02 MONITOR

DEVICE	REVISION	DATE CD	LOT NUMBER	PINS	PACKAGE	WIDTH	ASSEMBLY SITE
DS21S07	C1-A	0112	DM048483ACB	20	TSSOP	4.4x0.9	Carsem
PROCESS 1P, 1M, 0.8um,Neg ZTC P1R,PdpID,Low Laser/Nit - Pass/Nit - General LaserPrb							

Summary Data with Chi-Square Distribution Assumed.
 Stress Ambient Temperature and Voltage to
 Field Ambient Temperature And Voltage

Cf:	<u>60%</u>	Tuse:	<u>25 °C</u>
Ea:	<u>0.7</u>	Vuse:	<u>5.5 Volts</u>
β:	<u>0</u>		

JOB NO	DESCRIPT	CONDITION	QUANTITY	READPOINT	UNITS	NO OF FAILS
28811	AUTOCLAVE	121C, 2 ATM STEAM, UNBIASED	34	168	HRS	0
TOTAL:						0

RELIABILITY MONITOR

DS2401 AUG '02 MONITOR

DEVICE	REVISION	DATE CD	LOT NUMBER	PINS	PACKAGE	WIDTH	ASSEMBLY SITE
DS2401	C2	0245	DU218017AG	3	TO92	150	Hana
PROCESS 1P, 1M, 0.6um, Pd, Ti/TiN M1 , WJ Laser/TEOS Ox - Pass/Nit - Gen.LaserPrb							

Summary Data with Chi-Square Distribution Assumed.
 Stress Ambient Temperature and Voltage to
 Field Ambient Temperature And Voltage

Cf:	60%	Tuse:	25 °C
Ea:	0.7	Vuse:	5.5 Volts
β:	0		

JOB NO	DESCRIPT	CONDITION	QUANTITY	READPOINT	UNITS	NO OF FAILS
30203	HIGH VOLTAGE LIFE	125C, 6.0 VOLTS	80	500	HRS	0
		125C, 6.0 VOLTS	80	1000	HRS	0
		TOTAL:			FAIL RATE (Fits): 12	DEVICE HRS: 7.55E+07
30204	TEMP CYCLE	-55C TO 125C	45	500	CYS	1
			44	1000	CYS	0
		TOTAL:				
	FAILURE MODE	VERIFICATION	FA NUMBER	FAILURE MECHANISM		
	PD RESET	(#1)				
30205	HAST	130C, 85%R.H.,5.5V	77	96	HRS	0
		TOTAL:				0
30206	AUTOCLAVE	121C, 2 ATM STEAM, UNBIASED	45	168	HRS	0
		TOTAL:				0

PROJECT NO: 24621

RELIABILITY MONITOR

DS2502P APR '02 MONITOR

DEVICE	REVISION	DATE CD	LOT NUMBER	PINS	PACKAGE	WIDTH	ASSEMBLY SITE
DS2502	C4	0220	DE218054AEC	6	TSOC	150x1.2	OSEP

JOB_NO	DESCRIPTION	CONDITION	QUANTITY	READPOINT	UNITS	NO OF FAILS
29355	ULTRASOUND	J-STD-020	4	2	DYS	0
		TOTAL:				0
29356	STORAGE LIFE	125C	151	24	HRS	
	MOISTURE SOAK	85 C/85% R.H.	151	168	HRS	
	CONVECTION REFLOW	235C	151	3	PASS	0
		TOTAL:				0
29357	PRECONDITION U/S	J-STD-020	4	2	DYS	0
		TOTAL:				0
29358	TEMP CYCLE	-55C TO 125C	77	300	CYS	0
		-55C TO 125C	74	1000	CYS	0
		TOTAL:				0
29359	AUTOCLAVE	121C, 2 ATM STEAM, UNBIASED	69	96	HRS	0
		TOTAL:				0

PROJECT NO: 22619

RELIABILITY MONITOR

DS2502P JUL '02 MONITOR

DEVICE	REVISION	DATE CD	LOT NUMBER	PINS	PACKAGE	WIDTH	ASSEMBLY SITE
DS2502	C4	0238	DE252080AEB	6	TSOC	150x1.2	OSEP

JOB_NO	DESCRIPTION	CONDITION	QUANTITY	READPOINT	UNITS	NO OF FAILS
30107	ULTRASOUND	J-STD-020	4	2	DYS	0
		TOTAL:				0
30108	STORAGE LIFE	125C	151	24	HRS	
	MOISTURE SOAK	85 C/85% R.H.	151	168	HRS	
	CONVECTION REFLOW	235C	151	3	PASS	0
		TOTAL:				0
30110	TEMP CYCLE	-55C TO 125C	77	500	CYS	0
		-55C TO 125C	77	1000	CYS	
		TOTAL:				0
30111	AUTOCLAVE	121C, 2 ATM STEAM, UNBIASED	70	96	HRS	0
		TOTAL:				0

PROJECT NO: 24463

RELIABILITY MONITOR

DS80C320 DEC '02 MONITOR

DEVICE	REVISION	DATE CD	LOT NUMBER	PINS	PACKAGE	WIDTH	ASSEMBLY SITE
DS80C320	C5	0230	DK240563AB	40	PDIP	600	ATP (Amkor, PI)
PROCESS D6RL-1P1M,SILP1,LLVt,N+ESD PBL:G Passivation w/Nov TEOS Oxide-Nitride							

Summary Data with Chi-Square Distribution Assumed.
 Stress Ambient Temperature and Voltage to
 Field Ambient Temperature And Voltage

Cf:	<input type="text" value="60%"/>	Tuse:	<input type="text" value="25 °C"/>
Ea:	<input type="text" value="0.7"/>	Vuse:	<input type="text" value="5.5 Volts"/>
β:	<input type="text" value="0"/>		

JOB NO	DESCRIPT	CONDITION	QUANTITY	READPOINT	UNITS	NO OF FAILS
30259	HIGH VOLTAGE LIFE	125C, 7.0 VOLTS	77	500	HRS	0
		125C, 7.0 VOLTS	77	1000	HRS	0
		TOTAL:			FAIL RATE (Fits): 13	DEVICE HRS: 7.26E+07
30260	TEMP CYCLE	-55C TO 125C	45	500	CYS	0
			45	1000	CYS	0
		TOTAL:				
30261	BIASED MOISTURE	85/85, 5.5 VOLTS	77	500	HRS	0
		TOTAL:				
30262	AUTOCLAVE	121C, 2 ATM STEAM, UNBIASED	45	96	HRS	0
		TOTAL:				

PROJECT NO: 24680

RELIABILITY MONITOR

DS87C520 DEC '02 MONITOR

DEVICE	REVISION	DATE CD	LOT NUMBER	PINS	PACKAGE	WIDTH	ASSEMBLY SITE
DS87C520	A15-I	0232	DK241602AAA	44	PLCC	650x65	ATP (Amkor, PI)
PROCESS 2P, 1M, 0.8um,ThinEP/Sil,ThinOx NdPdD Passivation w/Nov TEOS Oxide-OxyNitride							

Summary Data with Chi-Square Distribution Assumed.
 Stress Ambient Temperature and Voltage to
 Field Ambient Temperature And Voltage

Cf:	60%	Tuse:	25 °C
Ea:	0.7	Vuse:	5.5 Volts
β:	0		

JOB NO	DESCRIPT	CONDITION	QUANTITY	READPOINT	UNITS	NO OF FAILS
30255	HIGH VOLTAGE LIFE	125C, 7.0 VOLTS	75	500	HRS	
TOTAL:			FAIL RATE (Fits):		DEVICE HRS: 3.54E+07	
30253	STORAGE LIFE	125C	239	24	HRS	
	MOISTURE SOAK	30C/60% R.H.	239	192	HRS	
	CONVECTION REFLOW	220C	239	3	PASS	0
TOTAL:			0			
30256	TEMP CYCLE	-55C TO 125C	50	500	CYS	0
			50	1000	CYS	0
TOTAL:			0			
30257	HAST	130C, 85%R.H.,5.5V	59	96	HRS	
TOTAL:						
30258	STORAGE LIFE	150C	50	500	HRS	
TOTAL:						

PROJECT NO: 24681